



Customer Information Notification

2023110081 : ASECL End-of-Service and Migration: Mold and Trim/Form Tools For Select NXP LQFP EP 80L Products

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 18, 2023 **Effective date:** Feb 18, 2024

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Management summary

NXP Semiconductors received an End-of-Service (EOS) announcement from assembly partner ASECL (ASE -Chungli, Taiwan) due to aging and obsolete mold machine Towa YPS 1.5 and de-junk / trim and form (DJTF) machine Yamada, which impacts select NXP LQFP EP 80L products associated with this notification. As a result, ASECL must migrate these impacted NXP products to new machines for supply assurance.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

PCN Overview

Description

NXP Semiconductors received an End-of-Service (EOS) announcement from assembly partner ASECL (ASE -Chungli, Taiwan) due to aging and obsolete mold machine Towa YPS 1.5 and de-junk / trim and form (DJTF) machine Yamada, which impacts select NXP LQFP EP 80L products associated with this notification. As a result, ASECL must migrate these impacted NXP products from obsolete mold machine Towa YPS 1.5 to newer mold machine ASM 170T, and from obsolete DJTF machine Yamada to newer DJTF / DDTF (de-dambar / trim and form) machine GPM for supply assurance.

Current mold machine Towa YPS 1.5 and DJTF machine Yamada aging condition (difficulty to maintain with lack of spare parts) creates excessive down-time and is a supply assurance liability which will be addressed with migration to newer ASM 170T and GPM machines. In addition, new DJTF GPM is more efficient, combining de-junk and trim and form operations in a single tool / station run vs old Yamada with separate de-junk operation, then reload product for trim and form operation. New mold ASM 170T and DJTF GPM machines are not “new” tools - only new for the identified

impacted products - and these machines are under extended, successful mass production at ASECL for other LQFP packages with varying lead counts.

The machine changes from Towa YPS 1.5 to ASM 170T and Yamada to GPM result in no product package drawing change, no dimensional change - exact same before and after. However, the machine changes do result in product visual differences:

1. Visual difference at mold eject pin marks, including top eject pin surface texture and bottom eject pin change from one pin mark to two pin marks.
2. Visual difference at the package lead area with base copper material now exposed due to de-junk and plating process flow sequence change as described below.

Current Yamada assembly backend process flow sequence:

Mold -> Laser Mark -> PMC (Post Mold Cure) -> De-Junk -> Plating -> Trim and Form -> FVI (Final Visual Inspection)

New GPM assembly backend process flow sequence:

Mold -> Laser Mark -> PMC (Post Mold Cure) -> Plating -> De-Junk and Trim and Form -> FVI (Final Visual Inspection)

Please see the attached change summary for additional details.

Corresponding ZVEI Delta Qualification Matrix Reference: SEM-PA-17, SEM-EQ-02

Reason

NXP assembly partner ASECL End-of-Service (EOS) announcement for obsolete mold machine Towa YPS 1.5 and de-junk / trim and form (DJTF) machine Yamada impact select NXP LQFP EP 80L products associated with this notification, and result in the migration to new mold and de-junk / trim and form machines for product supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No change to fit, function, reliability or quality. Change to product form only as described, with visual difference at package mold eject pin marks, and the package lead area with base material copper exposed due to de-junk and plating process flow sequence change.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Richard Schmidgall
Position	Product Quality Engineer

**e-mail
address**

richard.schmidgall@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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MC33PT2000AFR2	935318721528	MC33PT2000AFR2	eMGS3325	H(L)QFP80	SOT1572-1	RFS	No	BLC3